

2-GBPS Differential Repeater Evaluation Module

User's Guide

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It is important to operate this EVM within the supply voltage range of 3 V to 3.6 V.

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the supply range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than 125°C. The EVM is designed to operate properly with certain components above 125°C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

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Read This First

About This Manual

This EVM user's guide provides information about the 2-GBPS differential repeater evaluation module.

How to Use This Manual

This document contains the following chapters:

- Chapter 1 — Introduction
- Chapter 2 — Setup and Equipment Required
- Chapter 3 — EVM Construction

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This is an example of a caution statement.

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Data Sheet:

SN65LVDS100/101

Literature Number:

SLLS516

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This equipment is intended for use in a laboratory test environment only. It generates, uses, and can radiate radio frequency energy and has not been tested for compliance with the limits of computing devices pursuant to subpart J of part 15 of FCC rules, which are designed to provide reasonable protection against radio frequency interference. Operation of this equipment in other environments may cause interference with radio communications, in which case the user at his own expense will be required to take whatever measures may be required to correct this interference.

Contents

1	Introduction	1-1
1.1	Overview	1-2
1.2	Signal Paths	1-3
2	Setup and Equipment Required	2-1
2.1	Overview	2-2
2.2	Applying an Input	2-3
2.3	Observing an Output	2-5
2.4	Typical Test Results	2-6
3	EVM Construction	3-1
3.1	Schematic	3-2
3.2	Bill of Materials	3-3
3.3	Board Stackup	3-4
3.4	Board Layer Patterns	3-5

Figures

1-1	EVM With SN65LVDS100 Installed	1-2
1-2	Schematic of EVM Signal Path	1-3
2-1	TIA/EIA-644-A LVDS Driver Test Load	2-2
2-2	EVM Power Connections for SN65LVDS100 Evaluation	2-3
2-3	External Termination for Differential CML or LVPECL Inputs to EVM	2-4
2-4	External Termination for Single-Ended LVPECL Inputs to EVM	2-5
2-5	Typical Output From SN65LVDS100 EVM	2-6

Tables

1-1	Ordering Information	1-2
-----	----------------------------	-----

Introduction

The 2-GBPS differential repeater evaluation module (EVM) allows evaluation of the SN65LVDS100 and SN65LVDS101 differential repeaters/ translators. This user's guide gives a brief overview of the EVM, setup and operation instructions, and typical test results that can be expected.

Topic	Page
1.1 Overview	1-2
1.2 Signal Paths	1-3

1.1 Overview

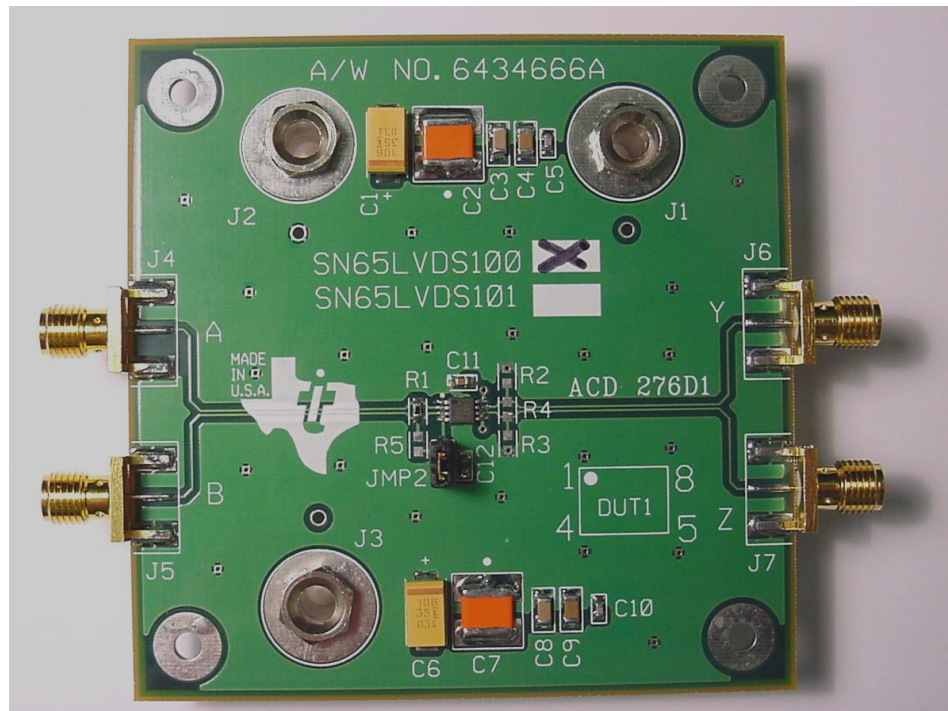
The 2-GBPS differential repeater evaluation module (EVM) is designed for evaluation of the SN65LVDS100 and SN65LVDS101 differential repeaters/translators. The SN65LVDS100 and SN65LVDS101 devices both incorporate wide common-mode range receivers, allowing receipt of LVDS, LVPECL, or CML input signals. The SN65LVDS100 provides an LVDS output, while the SN65LVDS101 incorporates an LVPECL output driver. Both devices provide a V_{BB} reference voltage to support receiving of single-ended LVPECL input signals, or biasing of ac-coupled inputs. The EVM can be ordered with the SN65LVDS100 or SN65LVDS101 installed. Orderable EVM part numbers are shown in Table 1-1.

Table 1-1. Ordering Information

EVM Part Number	Installed Device
SN65LVDS100EVM	SN65LVDS100DGK
SN65LVDS101EVM	SN65LVDS101DGK

Detailed information relating to the SN65LVDS100 and SN65LVDS101 can be found in the device data sheet, a copy of which is shipped as part of the EVM or available from www.ti.com. A picture of the EVM, with an SN65LVDS100 device installed, is shown in Figure 1-1.

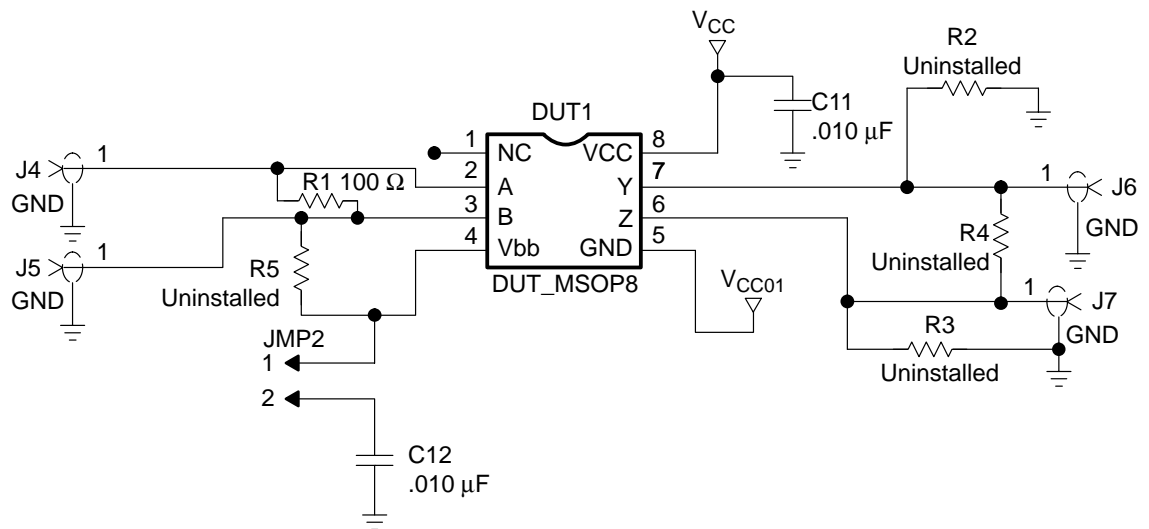
Figure 1-1. EVM With SN65LVDS100 Installed



1.2 Signal Paths

A partial schematic of the EVM is shown in Figure 1-2 and a full schematic is in chapter 3. Edge-mount SMA connectors (J4, J5, J6, and J7) are provided for data input and output connections. Three power jacks (J1, J2, and J3) are used to provide power to and a ground reference, for the EVM. The use of these power jacks is addressed later. Chapter 3 also provides a parts list for the EVM, as well as an indication of which components are installed when shipped.

Figure 1-2. Schematic of EVM Signal Path





Setup and Equipment Required

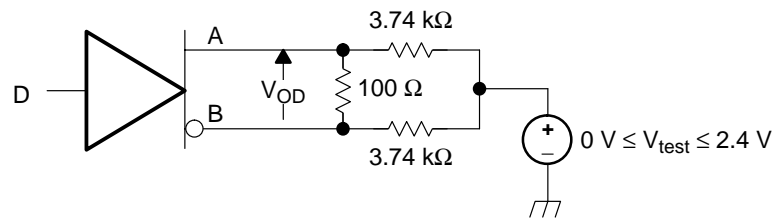
This chapter examines the setup and use of the evaluation module and the results of operation.

Topic	Page
2.1 Overview	2-2
2.2 Applying an Input	2-3
2.3 Observing an Output	2-5
2.4 Typical Test Results	2-6

2.1 Overview

LVDS driver output characteristics are specified in the TIA/EIA-644 standard. LVDS drivers nominally provide a 350-mV differential signal, with a 1.25-V offset from ground. These levels are attained when driving a 100- Ω differential line-termination test load (see Figure 2-1). In real applications, there may be a ground potential between a driver and receiver(s). The driver must drive the common-mode load presented by the receiver inputs and the differential load. A TIA/EIA-644-A compliant LVDS driver is required to maintain its differential output with up to 32 standard receivers. The receiver load is represented by the 3.74-k Ω resistors shown in Figure 2-1.

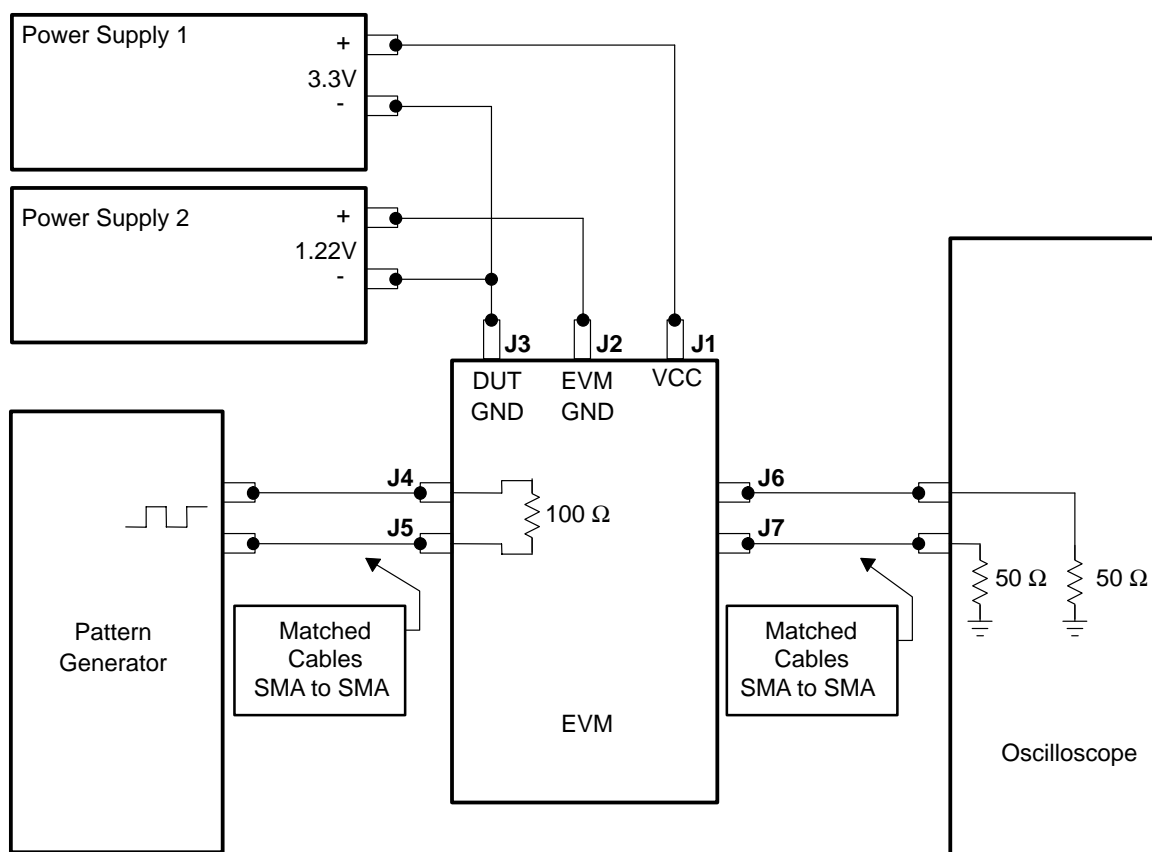
Figure 2-1. TIA/EIA-644-A LVDS Driver Test Load



LVPECL drivers are generally loaded with 50- Ω resistors to a termination bias voltage, V_T . V_T is usually 2-V below the supply voltage of the driver circuit. When the driver operates from a 3.3-V supply, V_T is set to approximately 1.3 V.

The EVM has been designed to support the SN65LVDS100 LVDS-output device as well as the SN65LVDS101 LVPECL-output device. By using the three power jacks (J1, J2, and J3), as well as installing termination resistors (R2, R3, and R4), different methods of termination and probing can be used to evaluate the device output characteristics. The typical setup for the SN65LVDS100 is shown in Figure 2-2.

Figure 2-2. EVM Power Connections for SN65LVDS100 Evaluation

**Warning**

Power jacks J1, J2, and J3 are not insulated on the backside of the EVM. Place on a nonconductive surface.

2.2 Applying an Input

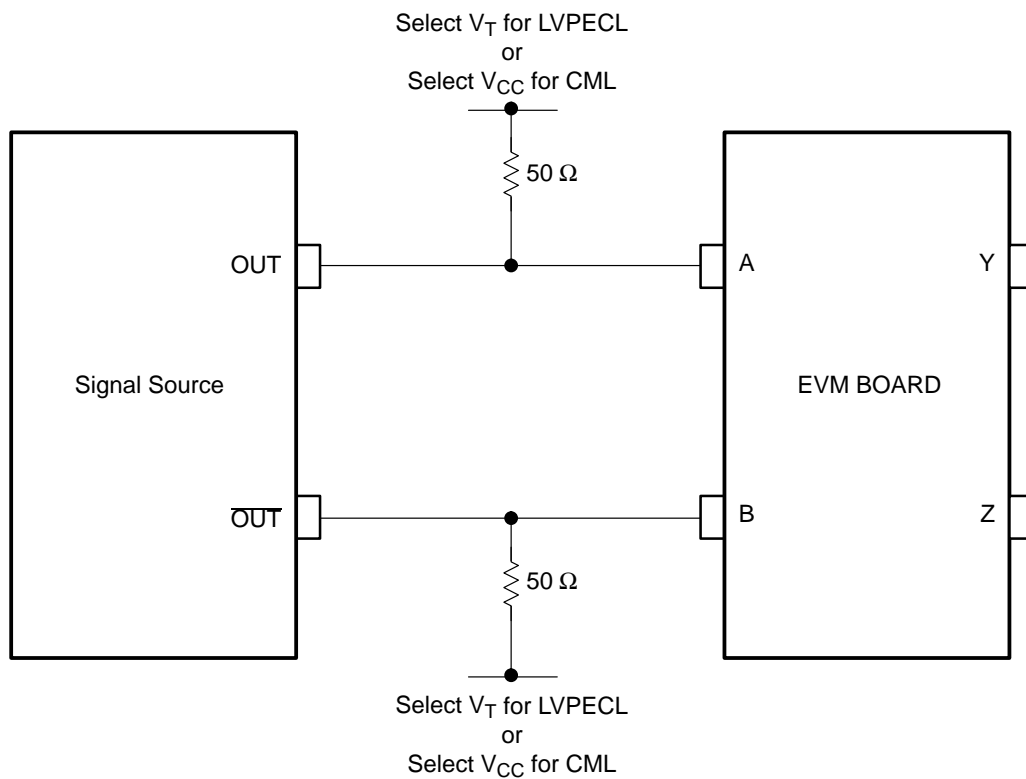
LVDS inputs should be applied to SMA connectors J4 and J5, while keeping R1 installed. The EVM comes with a 100-Ω termination resistor (R1) installed across the differential inputs. This 100-Ω resistor represents an LVDS termination.

When using a general-purpose signal generator with 50-Ω output impedance, make sure that the signal levels are between 0 V to 4 V with respect to J3. A signal generator such as the Advantest D3186 can simulate LVDS, LVPECL, or CML inputs.

When using LVPECL or CML drivers for the input signal, termination external to the EVM must be provided (see Figure 2-3). LVPECL drivers should be terminated with 50-Ω pulldowns to V_T , while CML drivers should be terminated

with 50-Ω pullups to V_{CC} . When using external terminations, the onboard termination resistor R1 should be removed from the EVM. It should be noted that the signal quality at the receiver input may be degraded when external terminations are used, as a significant stub exists from the external termination network to the receiver input. The user needs to verify that the transition time of the input signal, coupled with the stub length, does not lead to reflection problems. These concerns would be addressed in a real application where the terminations are placed close to the receiver input.

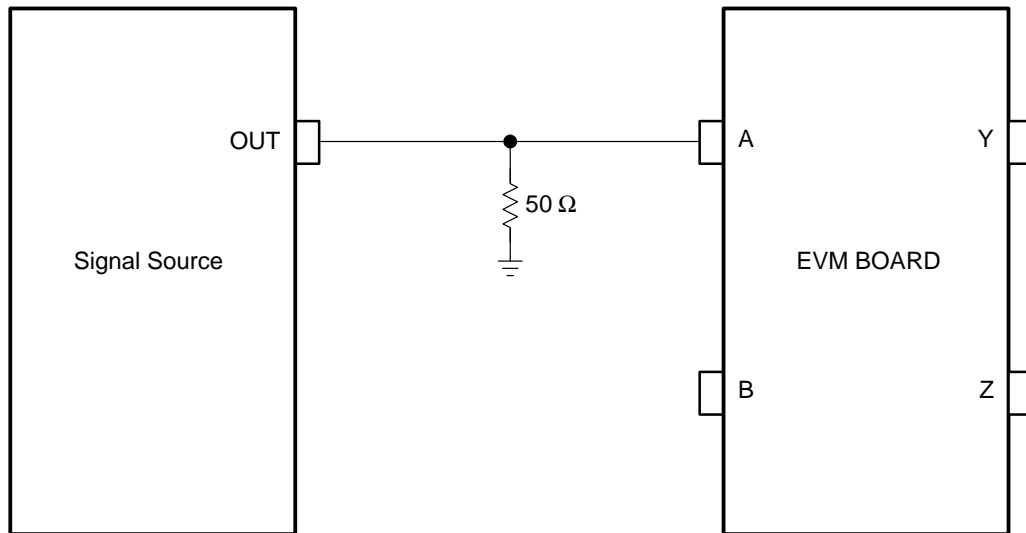
Figure 2-3. External Termination for Differential CML or LVPECL Inputs to EVM



- NOTES: A. Locate 50-Ω resistors as close to the EVM as possible
B. Remove R1

Finally, as mentioned above, the SN65LVDS100 and SN65LVDS101 devices provide a V_{BB} reference voltage output. This output can be used with an externally terminated, single-ended, LVPECL input to convert from a single-ended input to a differential output. The same cautions that are mentioned above concerning signal quality and reflections apply. When using V_{BB} as a single-ended reference, R1 should be removed while R5 and JMP2 should be installed. The single-ended input signal is applied to J4. This setup directly connects the V_{BB} output to the DUT receiver B input via a 0-Ω connection (see Figure 2-4).

Figure 2-4. External Termination for Single-Ended LVPECL Inputs to EVM



NOTES: A. Add jumper Jmp2 and 0-Ω R5
 B. Remove R1

2.3 Observing an Output

Direct connection to an oscilloscope with 50-Ω internal terminations to ground is accomplished without R2, R3, and R4¹. The outputs are available at J6 and J7 for direct connection to oscilloscope inputs. Matched length cables must be used when connecting the EVM to a scope to avoid inducing skew between the noninverting (+) and inverting (-) outputs.

The three power jacks (J1, J2, and J3) are used to provide power and a ground reference for the EVM. The power connections to the EVM determine the common-mode load to the device. As mentioned earlier, LVDS drivers have limited common-mode driver capability. When connecting the EVM outputs directly to oscilloscope inputs, setting of the oscilloscope common-mode offset voltage is required, as the oscilloscope presents low common-mode load impedance to the device.

Returning to Figure 2-2, power supply 1 is used to provide the required 3.3 V to the EVM. Power supply 2 is used to offset the EVM ground relative to the DUT ground. The EVM ground is connected to the oscilloscope ground through the returns on SMA connectors J6 and J7. With power applied as shown in Figure 2-2, the common-mode voltage seen by the SN65LVDS100 is approximately equal to the reference voltage being used inside the device preventing significant common-mode current to flow. Optimum device setup can be confirmed by adjusting the voltage on power supply 2 until its current is minimized. It is important to note that use of the dual supplies and offsetting the EVM ground relative to the DUT ground are simply steps needed for the test and evaluation of devices. Actual designs would include high-impedance receivers, which would not require the setup steps outlined above.

¹ As delivered R2, R3, and R4 are not installed

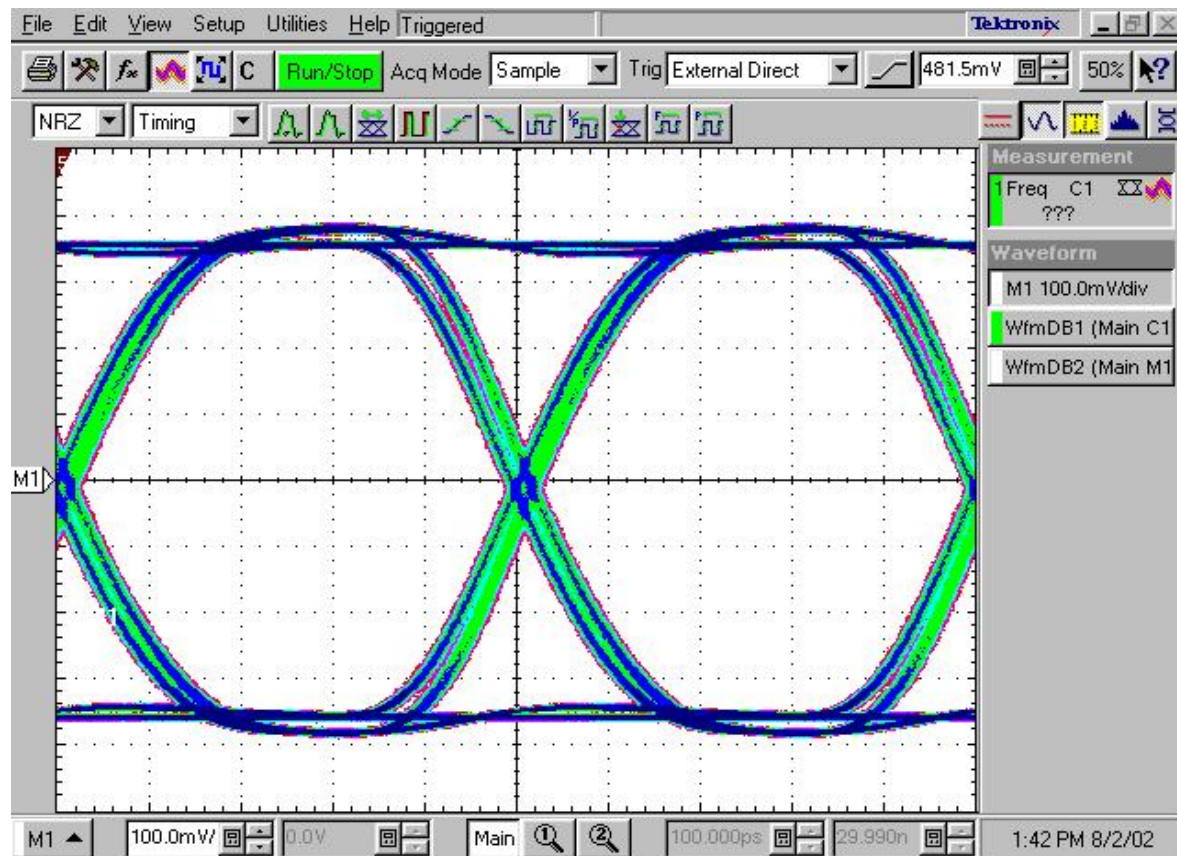
LVPECL drivers need a 50-Ω termination to V_T . A modification of Figure 2-2 and the above instructions are used when evaluating an SN65LVDS101 with a direct connection to a 50-Ω oscilloscope. With power supply 1 in Figure 2-2 set to 3.3 V, power supply 2 should be set to 1.3 V (2 V below V_{CC}) to provide the correct termination voltage.

If the EVM outputs are to be evaluated with a high-impedance probe, direct probing on the EVM is supported via installation of R2, R3, and R4. LVDS outputs can be observed by installing R4, a 100-Ω resistor. LVPECL outputs can be observed by installing R2 and R3 (49.9-Ω resistors), and setting power supply 2 to 1.3 V. (Note that power supply 2 must be able to sink current.)

2.4 Typical Test Results

Figure 2-5 shows a typical test result obtained with the EVM. Figure 2-5 shows the output of an SN65LVDS100 being driven directly into a 50-Ω oscilloscope. For this figure, the SN65LVDS100 was stimulated with a HP 3-GBPS BERT. The input data was pseudorandom data at 2 GBPS and with a random record length of $2^{23}-1$. The BERT drove two electrically matched one-meter cables with an electrical length of 3.667 ns. These cables were then connected to the EVM inputs. The EVM outputs were connected through another set of electrically matched one-meter cables and terminated by a TDS8000 oscilloscope's 50-Ω resistors to ground.

Figure 2-5. Typical Output From SN65LVDS100 EVM

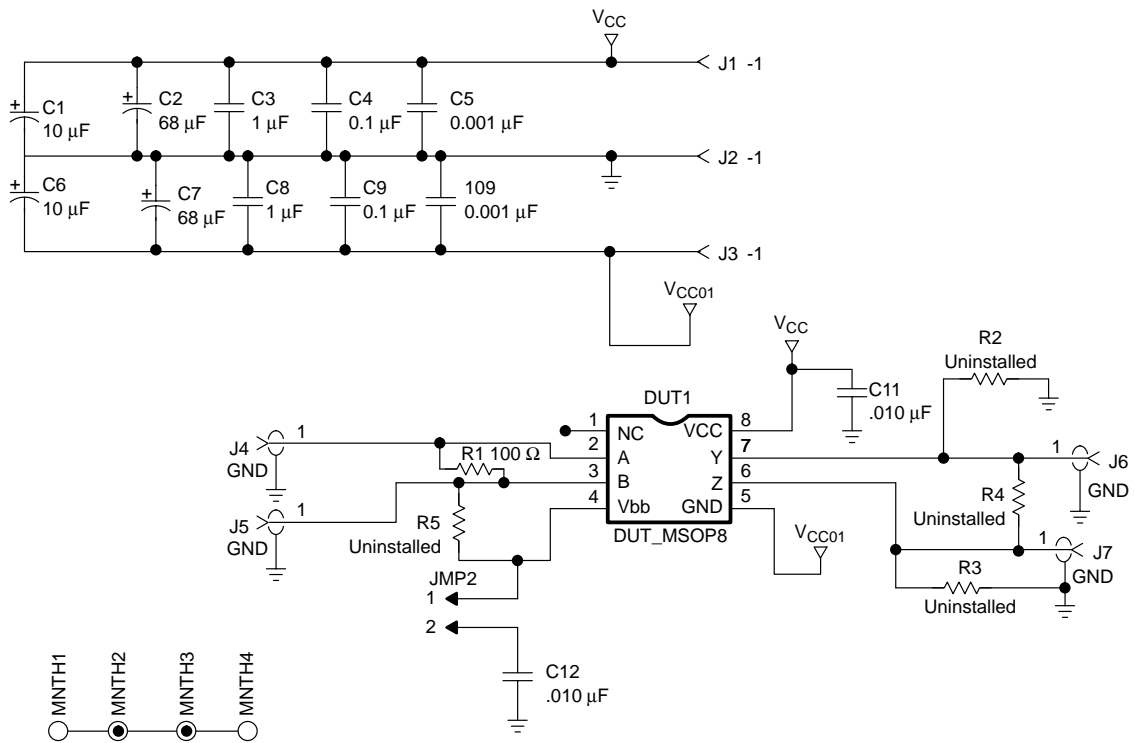


EVM Construction

This chapter lists the EVM components and examines the construction of the evaluation module.

Topic	Page
3.1 Schematic	3-2
3.2 Bill of Materials	3-3
3.3 Board Stack Up	3-4
3.4 Board Layer Patterns	3-5

3.1 Schematic



3.2 Bill of Materials

ITEM	QTY	MFG	MFG PART NO.	REF. DES.	DESCRIPTION	VALUE OR FUNCTION	NOT INSTALLED
1	2	Sprague	293D106X0035D2W	C1,C6	Capacitor, SMT, TANT	35 V, 10%, 10 μ F	
2	2	AVX	12063G105ZATRA	C3,C8	Capacitor, SMT1206	25 V, 80 -20%, 1.0 μ F	
3	2	AVX	12065C104JATMA	C4,C9	Capacitor, SMT1206	50 V, 5%, 0.1 μ F	
4	2	Sprague	592D686X0010R2T	C2,C7	Capacitor, SMT, TANT	10 V, 20%, 68 μ F, Low ESR	
5	2	Murata	GRM39X7R103K50V	C11, C12	Capacitor, SMT0603	50 V, \pm 10%, 0.010 μ F	
6	2	AVX	06033G102JATMA	C5,C10	Capacitor, SMT0603	25 V, 5%, 0.001 μ F	
7	3	ITT-Pomona	3267	J1, J2, J3	Connector, banana jack	Bannana jack	
8	4	EF Johnson	142-0701-801	J4, J5, J6, J7	Connector	SMA Jack, end launch, 0.062	
9	1	Dale	CRCW0603100F	R1	Resistor, SMT,0603	100 Ω	
10	2			R2, R3	Resistor, SMT, 0603	49.9 Ω	R2, R3
11	1			R4	Resistor, SMT, 0603	100 Ω	R4
12	1			R5	Resistor, SMT, 0603	0 Ω	R5
13	1	AMP	4-103239-0x2	JMP2	Header	Male, 2 pin, 0.100 CC	
14	1	TI	SN65LVDS100† SN65LVDS101†	DUT1	IC, SMT, 8P	2-GBPS differential repeater/translator	
15	3				Screws		
16	3				Nuts		
17	1				User's manual		
18	1				Data sheet		

† Only one is installed

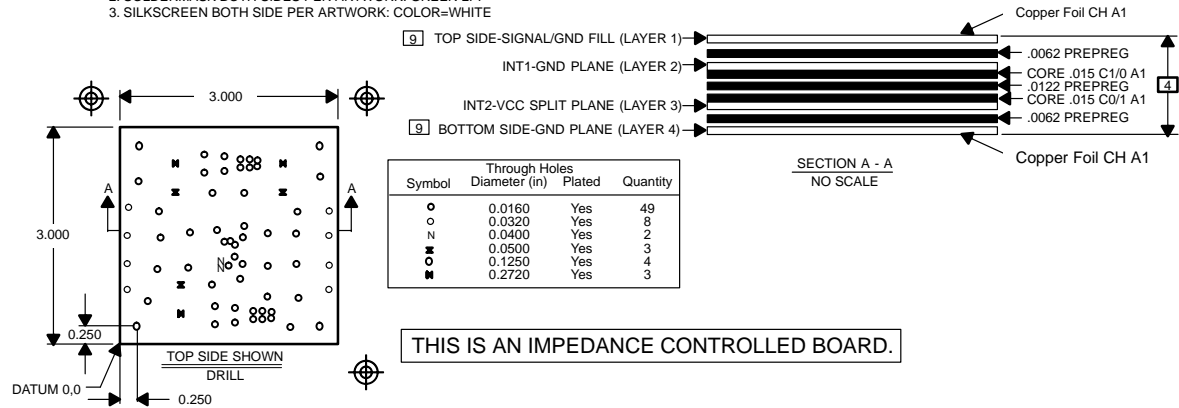
3.3 Board Stackup

GENERAL NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL FABRICATION ITEMS MUST MEET OR EXCEED BEST INDUSTRY PRACTICE. IPC-A 600C (Commercial Std.)
- 2.LAMINATE MATERIAL: NELCO N4000-13 (DO NOT USE - 13SI)
3. COOPER WEIGHT:1 OZ. START INTERNAL AND 1/2 OZ. START EXTERNAL
- 4] FINISHED BOARD THICKNESS: .062 ±10%
5. MAXIMUM WARP AND TWIST TO BE .005 INCH PER INCH
- 6 MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH
- 7 MINIMUM ANNULAR RING OF PLATED-THRU HOLES TO BE .002 INCH
8. MINIMUM ALLOWABLE LINE REDUCTION TO BE 20% OR .002 WHICHEVER IS GREATER
- 9] 0.013 INCH SIGNAL LINES ON LAYER 1 TO BE IMPEDANCE CONTROLLED 50 OHMS TO GND ±10%
0.010 INCH SIGNAL LINES ON LAYER 1 TO BE IMPEDANCE CONTROLLED 100 OHMS TO EACH OTHER ±10%
10. DIELECTRIC CONSTANTS ARE:
CORE: 3.2
PREPREG:3.2

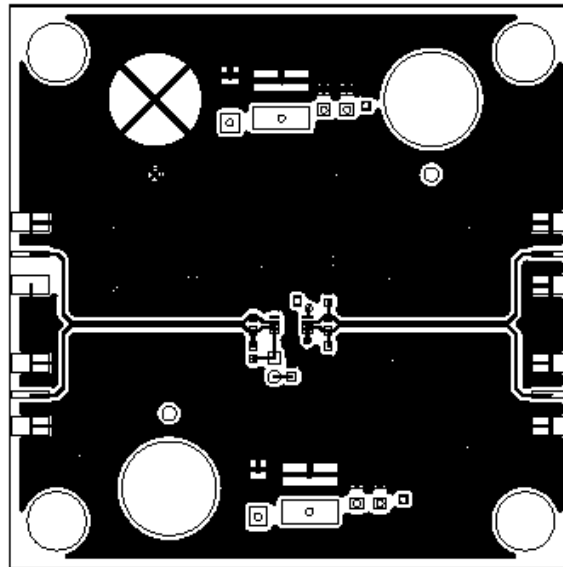
PROCESS NOTES:

1. CIRCUITRY ON OUTER LAYERS TO BE PLATED WITH TIN LEAD
2. SOLDERMASK BOTH SIDES PER ARTWORK: GREEN LPI
3. SILKSCREEN BOTH SIDE PER ARTWORK: COLOR=WHITE

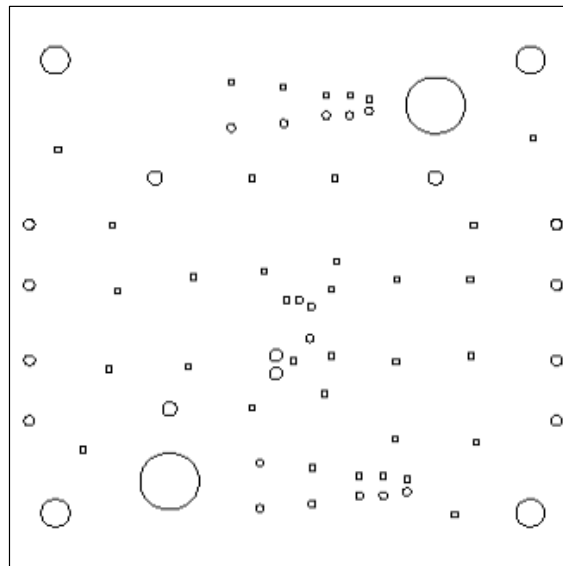


3.4 Board Layer Patterns

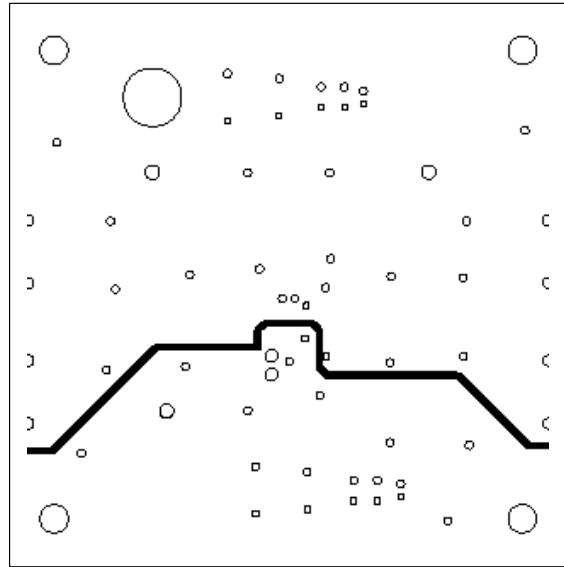
(Not to Scale)



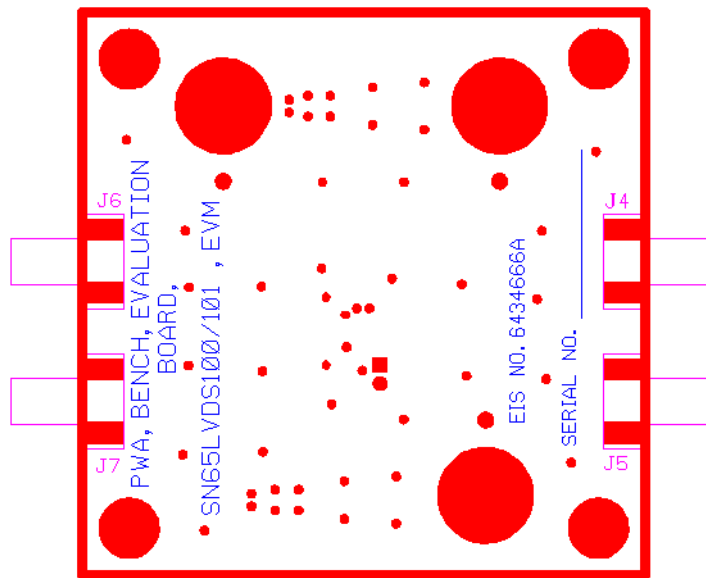
Layer 1 - Signal/GND Fill (Top Side)



Layer 2 - GND Plane (INT1)



Layer 3 - VCC Split Plane (INT2)



Layer 4 - GND Plane (Bottom Side)